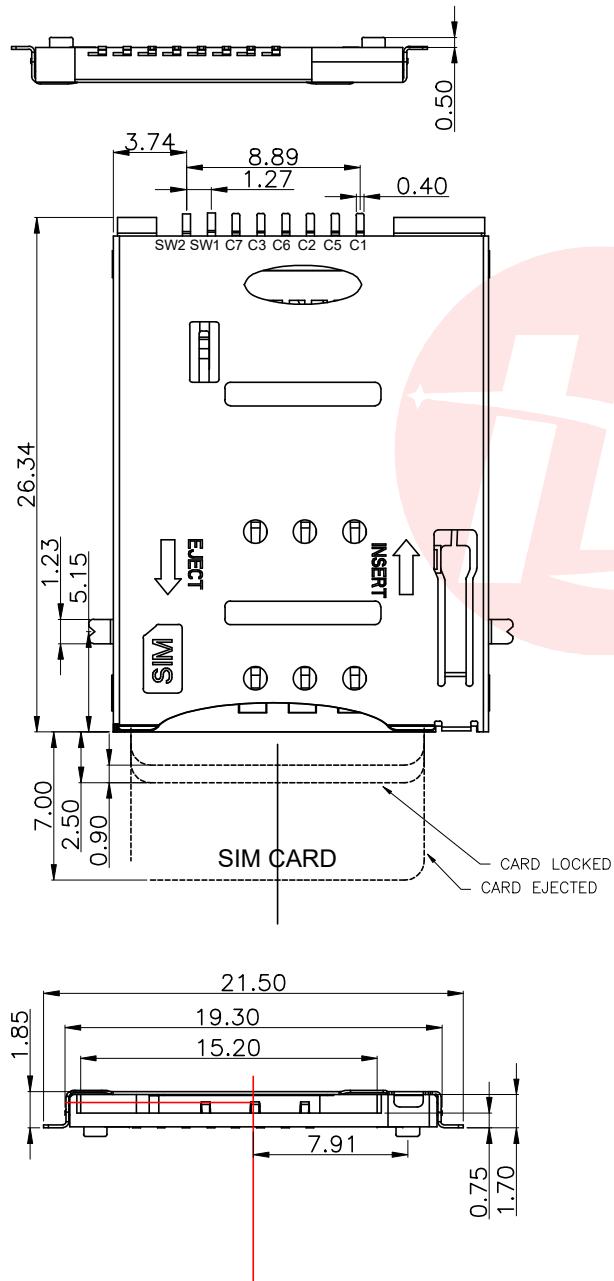




Specification

MATERIAL:

Insulator: High Temperature Thermoplastic,
UL 94V-0. COLOR"BLACK" LCP
(塑胶: 黑色LCP, 防火等级UL 94V-0)

Contact: Copper Alloy

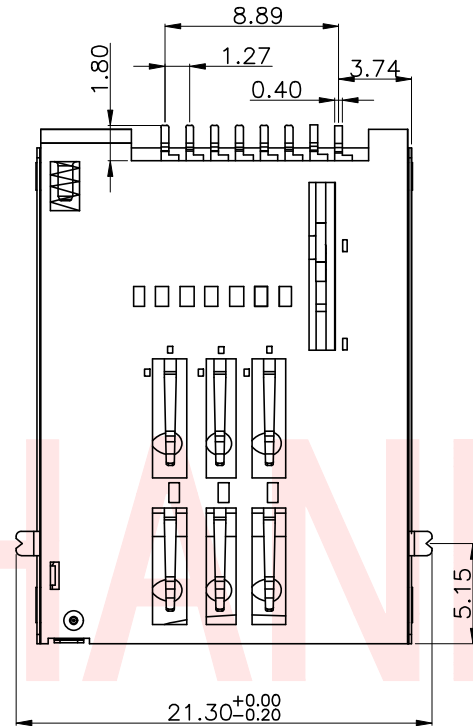
PLATING:

Contact: Plated 50u" Ni Overall
Plated Au Selective Contact Area
Plated 100u" Sn Over Ni On Solder Area
(接触端子电镀: 全铜镀50U, 接触区域1U金, 焊脚镀50U/最少)

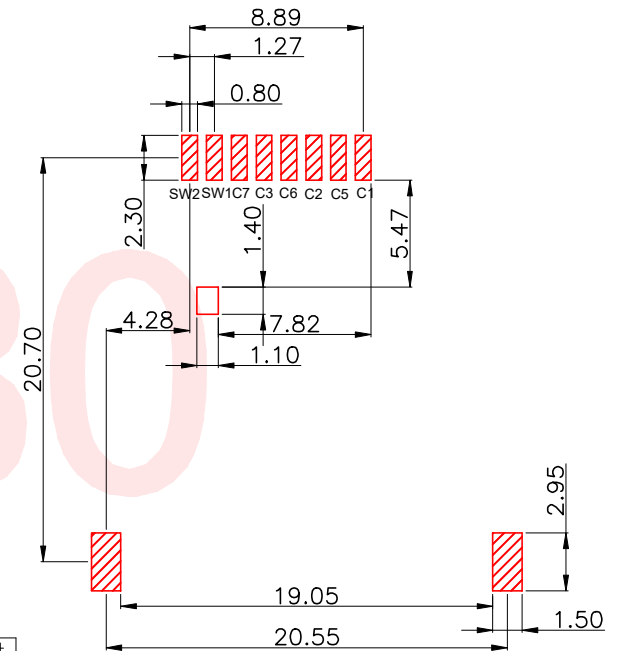
Shell: Plated 50u" Ni Overall
Plated 1u"Au Selective Contact Area
(外壳电镀: 镀50U, 焊脚镀1U金)

Electrical:

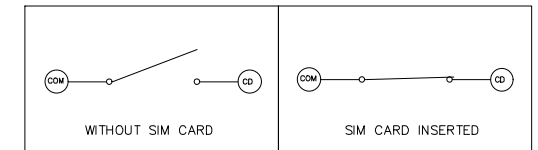
Current Rating :0.5Amps max(额定电流:0.5A最大)
Voltage Rating :5V AC/DC(额定电压:5V AC/DC)
Ambient Temperature Range :-20°C~+60°C(工作温度: -20度到+60度)
Storage Temperature Range :-40°C~+70°C(存储温度: -20度到+80度)
Ambient Humidity Range :95% R.H. Max. (相对湿度: 95%以下)
Contact Resistance:100mΩ max.(端子接触电阻: 100mΩ 最大)
Insulation Resistance:1000MΩ min./500VDC(绝缘电阻: 100兆欧最小)
Mating Cycles:5,000 Insertions (寿命: 5000次)
产品存储温度: 260°C



SIM pin assignment	
PIN#	Name
C1	VCC 电压
C2	RST 重置
C3	CLK 时钟
C5	GND 接地
C6	VPP 电压
C7	I/O 输入输出



RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05



UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X :±0.25	X :±2°
X.X :±0.10	X.X :±1°
X.XX :±0.05	

 东莞市汉博电子科技有限公司
DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE	Mini Sim Card Push Push 6+2P Smt无桩			
DWN	xiong	SIM-208		
CHKD	lee	SCALE:1:1	UNIT: mm	
APVD	wang	SIZE: A4	SHEET:1OF 1	REV: A4
CUSTOMER COPY				